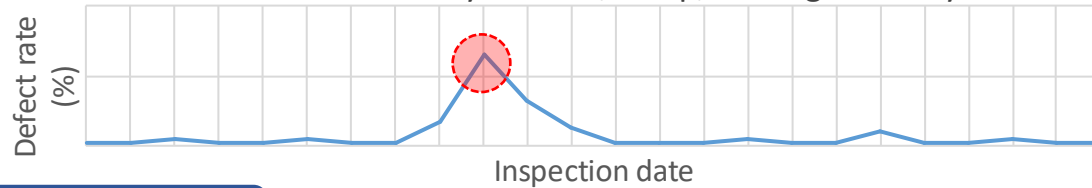


# Identified and Resolved an ESD Defect Spike via Dielectric Thickness Control

## Problem

### ESD defect rate spike

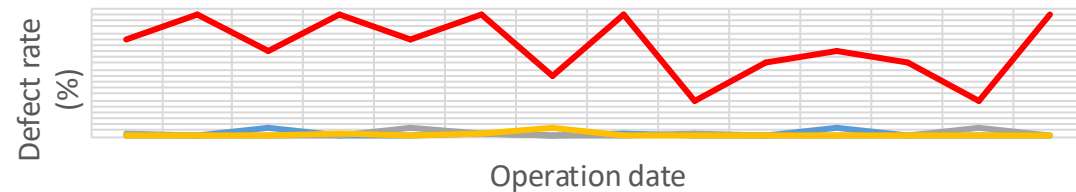
- A sudden spike in the electrostatic discharge (ESD) defect rate occurred
- This defect caused reliability failures, scrap, and significant yield loss



## Investigation

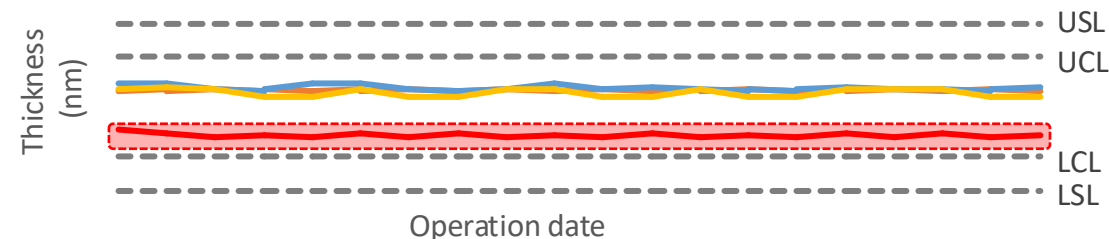
### Tool-to-tool defect rate variation

- **One photolithography coater** showed a **higher defect rate** than others
- Confirmed through tool-level analysis at a specific process step



### Lower thickness

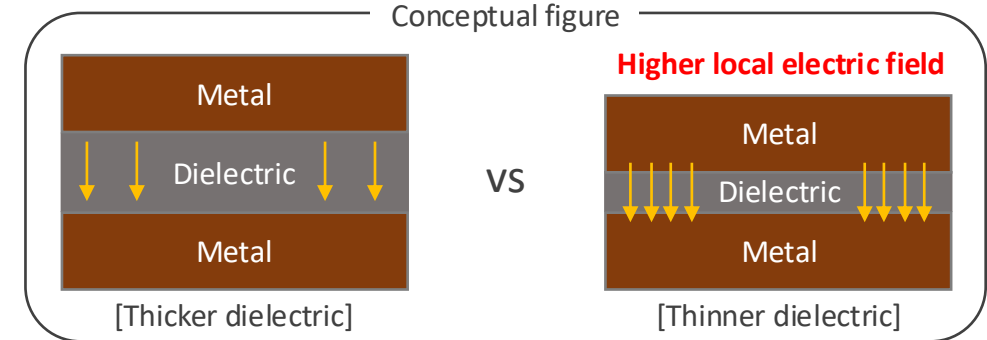
- The same photolithography coater produced a **thinner layer**
- Confirmed by inline thickness monitoring data and SEM analysis



## Hypothesis

### Capacitive coupling effect

- Thinner dielectrics in the capacitive stack led to higher local electric fields, increasing ESD susceptibility



## Verification

### Higher thickness target

- Resulted in a **lower defect rate** in tool-level pre/post comparisons

### SEM analysis

- Showed that most ESD-defective samples had thinner dielectric layers

## Action

### Thickness spec & control limit

- **Adjusted the thickness target** and **redefined spec** with related teams

### Thickness monitoring

- Implemented automated thickness monitoring with email alerts
- Increased thickness measurement frequency